



# PMN28UNE

20 V, N-channel Trench MOSFET

16 April 2018

Product data sheet

## 1. General description

N-channel enhancement mode Field-Effect Transistor (FET) in a small SOT457 (SC-74) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

## 2. Features and benefits

- Trench MOSFET technology
- Low threshold voltage
- Very fast switching
- ElectroStatic Discharge (ESD) protection > 2 kV HBM

## 3. Applications

- Relay driver
- High-speed line driver
- Low-side load switch
- Switching circuits

## 4. Quick reference data

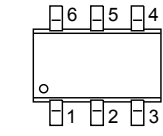
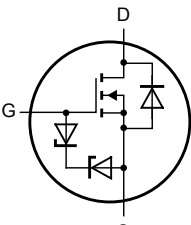
Table 1. Quick reference data

| Symbol                        | Parameter                        | Conditions                                                               |     | Min | Typ | Max | Unit |
|-------------------------------|----------------------------------|--------------------------------------------------------------------------|-----|-----|-----|-----|------|
| $V_{DS}$                      | drain-source voltage             | $T_j = 25\text{ °C}$                                                     |     | -   | -   | 20  | V    |
| $V_{GS}$                      | gate-source voltage              |                                                                          |     | -8  | -   | 8   | V    |
| $I_D$                         | drain current                    | $V_{GS} = 4.5\text{ V}$ ; $T_{amb} = 25\text{ °C}$ ; $t \leq 5\text{ s}$ | [1] | -   | -   | 7.1 | A    |
| <b>Static characteristics</b> |                                  |                                                                          |     |     |     |     |      |
| $R_{DS(on)}$                  | drain-source on-state resistance | $V_{GS} = 4.5\text{ V}$ ; $I_D = 5.5\text{ A}$ ; $T_j = 25\text{ °C}$    |     | -   | 24  | 32  | mΩ   |

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain 6 cm<sup>2</sup>.

5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline                                                                                  | Graphic symbol                                                                                   |
|-----|--------|-------------|-----------------------------------------------------------------------------------------------------|--------------------------------------------------------------------------------------------------|
| 1   | D      | drain       | <br>TSOP6 (SOT457) | <br>017aaa255 |
| 2   | D      | drain       |                                                                                                     |                                                                                                  |
| 3   | G      | gate        |                                                                                                     |                                                                                                  |
| 4   | S      | source      |                                                                                                     |                                                                                                  |
| 5   | D      | drain       |                                                                                                     |                                                                                                  |
| 6   | D      | drain       |                                                                                                     |                                                                                                  |

6. Ordering information

Table 3. Ordering information

| Type number | Package |                                          |         |
|-------------|---------|------------------------------------------|---------|
|             | Name    | Description                              | Version |
| PMN28UNE    | TSOP6   | plastic, surface-mounted package (SC-74) | SOT457  |

7. Marking

Table 4. Marking codes

| Type number | Marking code |
|-------------|--------------|
| PMN28UNE    | 3G           |

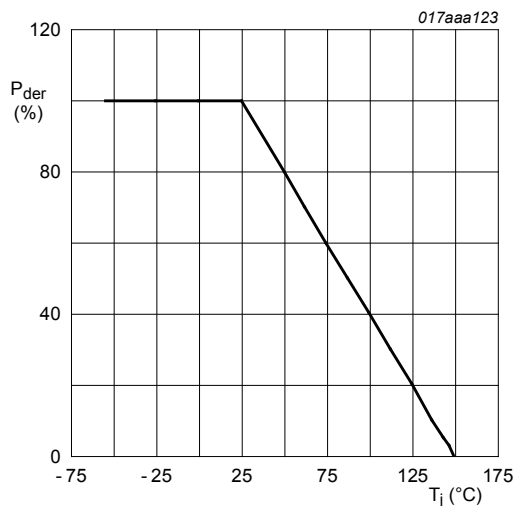
## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

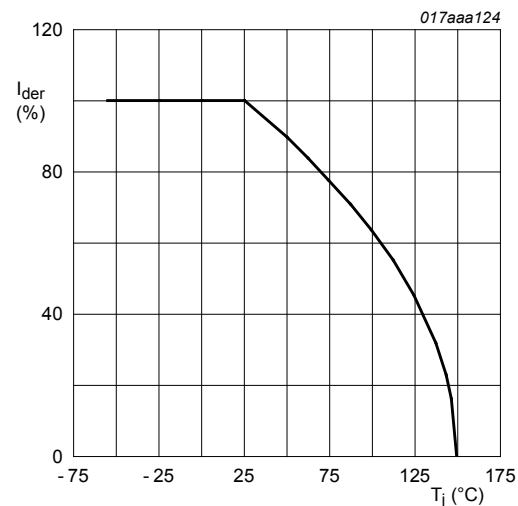
| Symbol                    | Parameter               | Conditions                                                     |     | Min | Max  | Unit |
|---------------------------|-------------------------|----------------------------------------------------------------|-----|-----|------|------|
| V <sub>DS</sub>           | drain-source voltage    | T <sub>j</sub> = 25 °C                                         |     | -   | 20   | V    |
| V <sub>GS</sub>           | gate-source voltage     |                                                                |     | -8  | 8    | V    |
| I <sub>D</sub>            | drain current           | V <sub>GS</sub> = 4.5 V; T <sub>amb</sub> = 25 °C; t ≤ 5 s     | [1] | -   | 7.1  | A    |
|                           |                         | V <sub>GS</sub> = 4.5 V; T <sub>amb</sub> = 25 °C              | [1] | -   | 5.5  | A    |
|                           |                         | V <sub>GS</sub> = 4.5 V; T <sub>amb</sub> = 100 °C             | [1] | -   | 3.5  | A    |
| I <sub>DM</sub>           | peak drain current      | T <sub>amb</sub> = 25 °C; single pulse; t <sub>p</sub> ≤ 10 μs |     | -   | 23   | A    |
| P <sub>tot</sub>          | total power dissipation | T <sub>amb</sub> = 25 °C                                       | [2] | -   | 570  | mW   |
|                           |                         |                                                                | [1] | -   | 1.4  | W    |
|                           |                         | T <sub>sp</sub> = 25 °C                                        |     | -   | 6.25 | W    |
| T <sub>j</sub>            | junction temperature    |                                                                |     | -55 | 150  | °C   |
| T <sub>amb</sub>          | ambient temperature     |                                                                |     | -55 | 150  | °C   |
| T <sub>stg</sub>          | storage temperature     |                                                                |     | -65 | 150  | °C   |
| <b>Source Drain Diode</b> |                         |                                                                |     |     |      |      |
| I <sub>S</sub>            | source current          | T <sub>amb</sub> = 25 °C                                       | [1] | -   | 1.3  | A    |

- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain 6 cm<sup>2</sup>.  
 [2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.



$$P_{der} = \frac{P_{tot}}{P_{tot(25^\circ C)}} \times 100 \%$$

**Fig. 1. Normalized total power dissipation as a function of junction temperature**



$$I_{der} = \frac{I_D}{I_{D(25^\circ C)}} \times 100 \%$$

**Fig. 2. Normalized continuous drain current as a function of junction temperature**

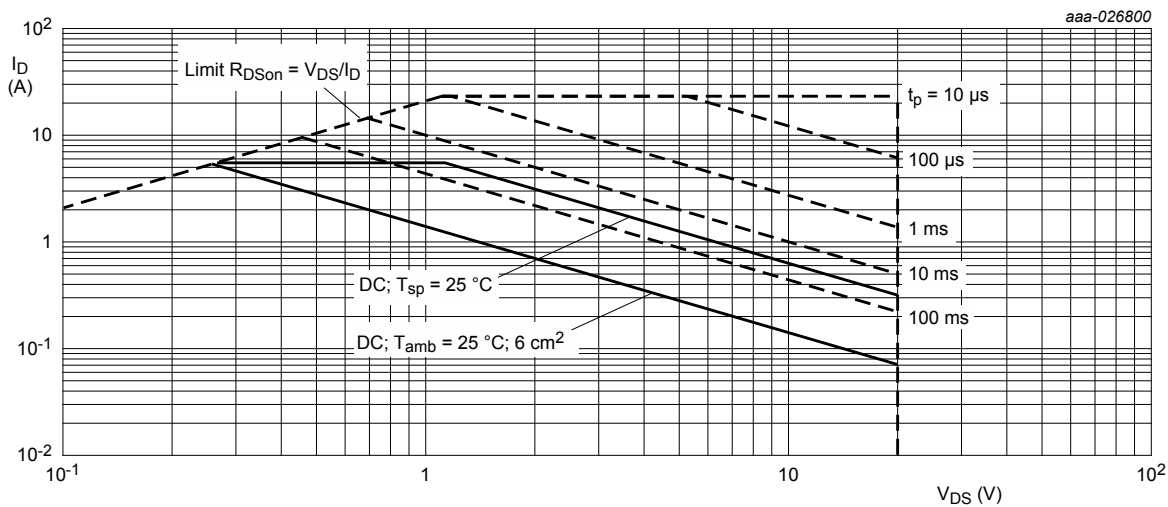


Fig. 3. Safe operating area; junction to ambient; continuous and peak drain currents as a function of drain-source voltage

9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol         | Parameter                                        | Conditions                |     | Min | Typ | Max | Unit |
|----------------|--------------------------------------------------|---------------------------|-----|-----|-----|-----|------|
| $R_{th(j-a)}$  | thermal resistance from junction to ambient      | in free air               | [1] | -   | 190 | 220 | K/W  |
|                |                                                  |                           | [2] | -   | 78  | 90  | K/W  |
|                |                                                  | in free air; $t \leq 5$ s | [2] | -   | 47  | 54  | K/W  |
| $R_{th(j-sp)}$ | thermal resistance from junction to solder point |                           |     | -   | 15  | 20  | K/W  |

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.  
[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for drain 6 cm<sup>2</sup>.

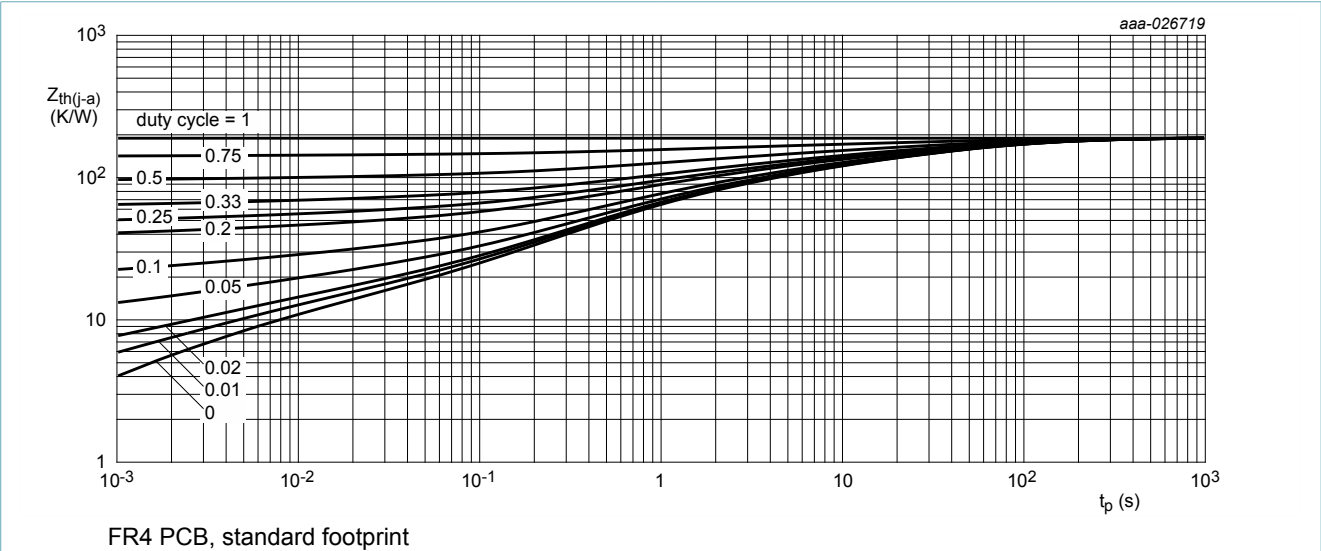


Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

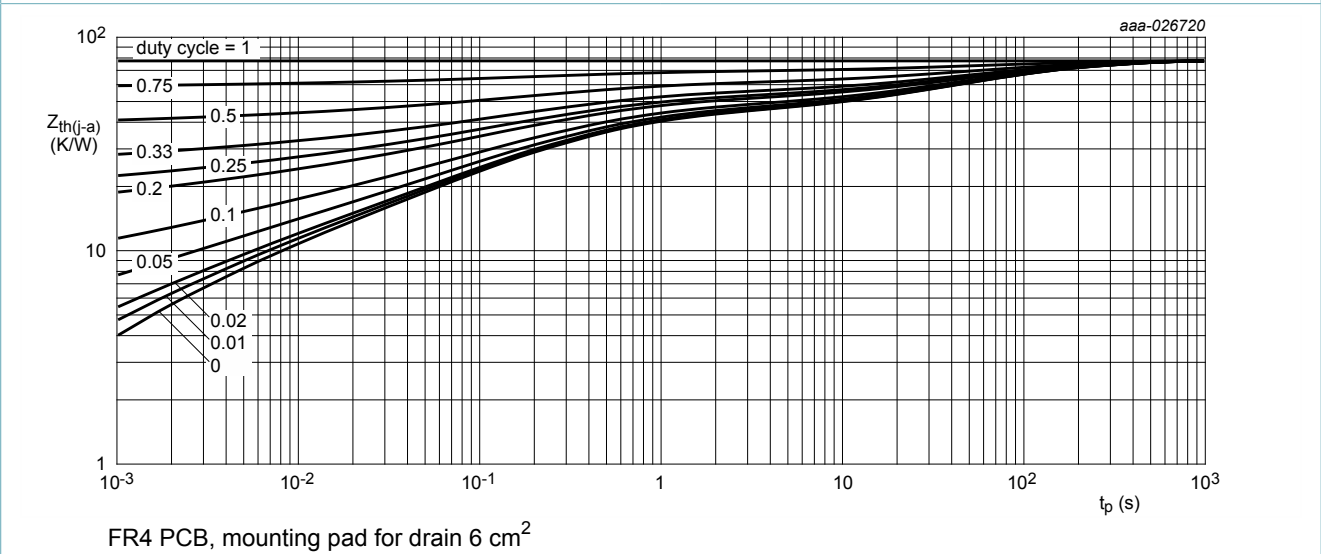


Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

## 10. Characteristics

Table 7. Characteristics

| Symbol                  | Parameter                        | Conditions                                                                                                                 |  | Min  | Typ | Max  | Unit |
|-------------------------|----------------------------------|----------------------------------------------------------------------------------------------------------------------------|--|------|-----|------|------|
| Static characteristics  |                                  |                                                                                                                            |  |      |     |      |      |
| V <sub>(BR)DSS</sub>    | drain-source breakdown voltage   | I <sub>D</sub> = 250 μA; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C                                                     |  | 20   | -   | -    | V    |
| V <sub>GSth</sub>       | gate-source threshold voltage    | I <sub>D</sub> = 250 μA; V <sub>DS</sub> = V <sub>GS</sub> ; T <sub>j</sub> = 25 °C                                        |  | 0.45 | 0.7 | 1    | V    |
| I <sub>DSS</sub>        | drain leakage current            | V <sub>DS</sub> = 20 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C                                                      |  | -    | -   | 1    | μA   |
| I <sub>GSS</sub>        | gate leakage current             | V <sub>GS</sub> = 20 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C                                                      |  | -    | -   | 10   | μA   |
|                         |                                  | V <sub>GS</sub> = -20 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C                                                     |  | -    | -   | -10  | μA   |
|                         |                                  | V <sub>GS</sub> = 4.5 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C                                                     |  | -    | -   | 5    | μA   |
|                         |                                  | V <sub>GS</sub> = -4.5 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C                                                    |  | -    | -   | -5   | μA   |
|                         |                                  | V <sub>GS</sub> = 2.5 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C                                                     |  | -    | -   | 100  | nA   |
|                         |                                  | V <sub>GS</sub> = -2.5 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C                                                    |  | -    | -   | -100 | nA   |
| R <sub>DSon</sub>       | drain-source on-state resistance | V <sub>GS</sub> = 4.5 V; I <sub>D</sub> = 5.5 A; T <sub>j</sub> = 25 °C                                                    |  | -    | 24  | 32   | mΩ   |
|                         |                                  | V <sub>GS</sub> = 4.5 V; I <sub>D</sub> = 5.5 A; T <sub>j</sub> = 150 °C                                                   |  | -    | 36  | 48   | mΩ   |
|                         |                                  | V <sub>GS</sub> = 2.5 V; I <sub>D</sub> = 4.7 A; T <sub>j</sub> = 25 °C                                                    |  | -    | 29  | 45   | mΩ   |
|                         |                                  | V <sub>GS</sub> = 1.8 V; I <sub>D</sub> = 1.3 A; T <sub>j</sub> = 25 °C                                                    |  | -    | 40  | 70   | mΩ   |
| g <sub>fs</sub>         | forward transconductance         | V <sub>DS</sub> = 10 V; I <sub>D</sub> = 4.7 A; T <sub>j</sub> = 25 °C                                                     |  | -    | 30  | -    | S    |
| R <sub>G</sub>          | gate resistance                  | f = 1 MHz                                                                                                                  |  | -    | 7   | -    | Ω    |
| Dynamic characteristics |                                  |                                                                                                                            |  |      |     |      |      |
| Q <sub>G(tot)</sub>     | total gate charge                | V <sub>DS</sub> = 10 V; I <sub>D</sub> = 4.7 A; V <sub>GS</sub> = 4.5 V; T <sub>j</sub> = 25 °C                            |  | -    | 6.2 | 10   | nC   |
| Q <sub>GS</sub>         | gate-source charge               |                                                                                                                            |  | -    | 0.5 | -    | nC   |
| Q <sub>GD</sub>         | gate-drain charge                |                                                                                                                            |  | -    | 1.4 | -    | nC   |
| C <sub>iss</sub>        | input capacitance                | V <sub>DS</sub> = 10 V; f = 1 MHz; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C                                           |  | -    | 490 | -    | pF   |
| C <sub>oss</sub>        | output capacitance               |                                                                                                                            |  | -    | 86  | -    | pF   |
| C <sub>rss</sub>        | reverse transfer capacitance     |                                                                                                                            |  | -    | 70  | -    | pF   |
| t <sub>d(on)</sub>      | turn-on delay time               | V <sub>DS</sub> = 10 V; I <sub>D</sub> = 4.7 A; V <sub>GS</sub> = 4.5 V; R <sub>G(ext)</sub> = 6 Ω; T <sub>j</sub> = 25 °C |  | -    | 8   | -    | ns   |
| t <sub>r</sub>          | rise time                        |                                                                                                                            |  | -    | 35  | -    | ns   |
| t <sub>d(off)</sub>     | turn-off delay time              |                                                                                                                            |  | -    | 39  | -    | ns   |
| t <sub>f</sub>          | fall time                        |                                                                                                                            |  | -    | 14  | -    | ns   |
| Source-drain diode      |                                  |                                                                                                                            |  |      |     |      |      |
| V <sub>SD</sub>         | source-drain voltage             | I <sub>S</sub> = 1.3 A; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C                                                      |  | -    | 0.7 | 1.2  | V    |

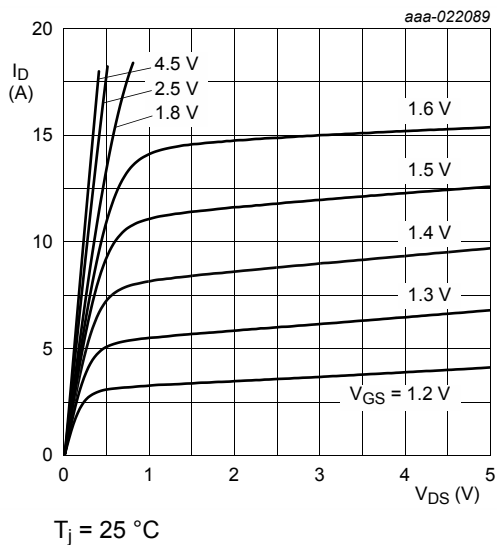


Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values

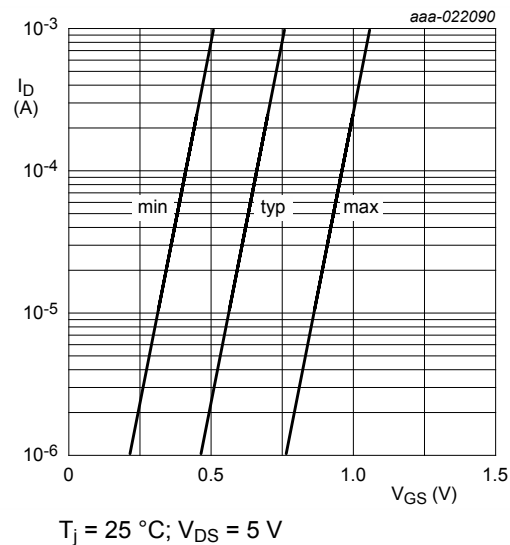


Fig. 7. Subthreshold drain current as a function of gate-source voltage

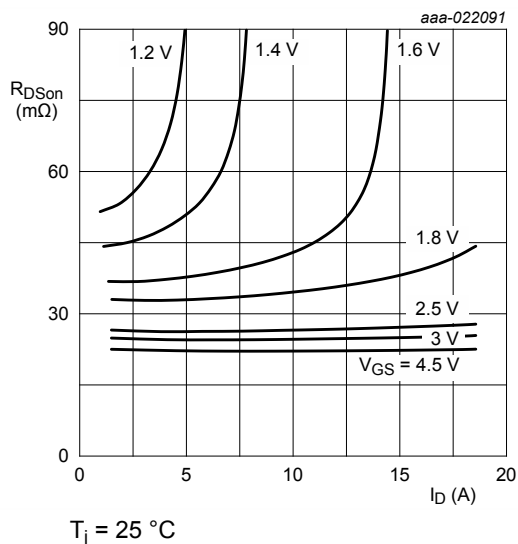


Fig. 8. Drain-source on-state resistance as a function of drain current; typical values

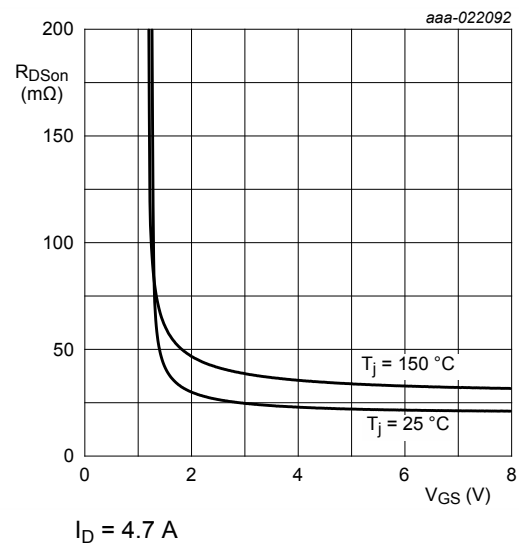


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

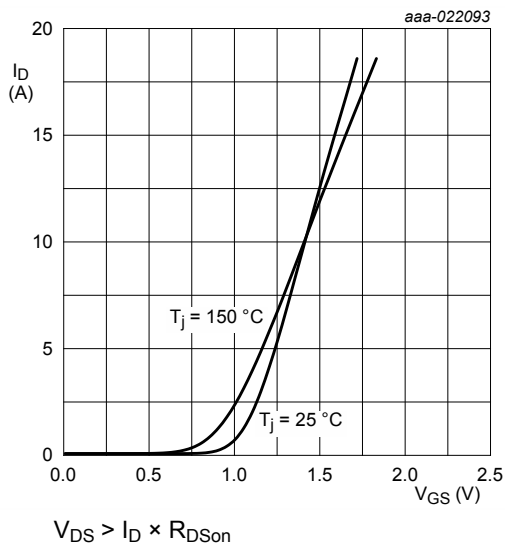


Fig. 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values

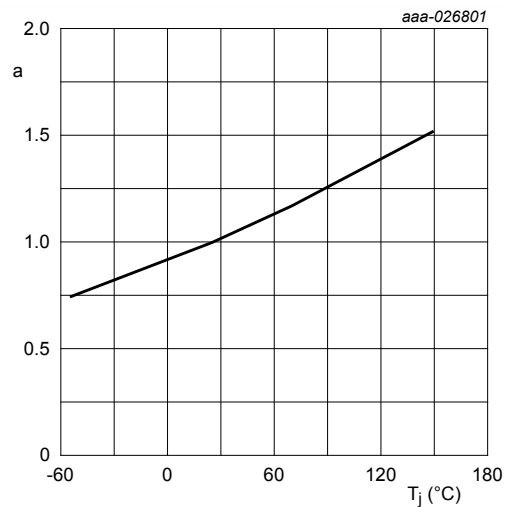


Fig. 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values

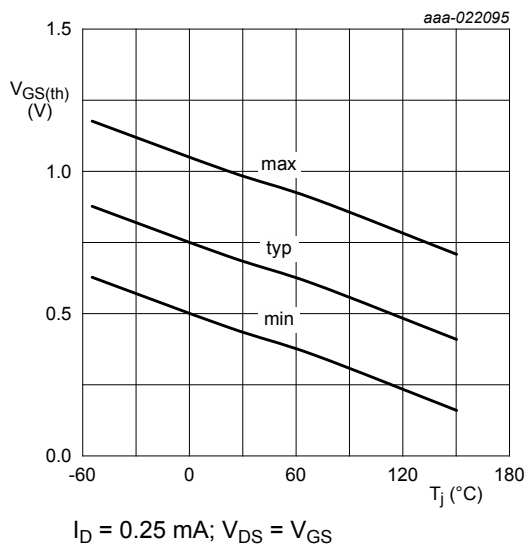


Fig. 12. Gate-source threshold voltage as a function of junction temperature

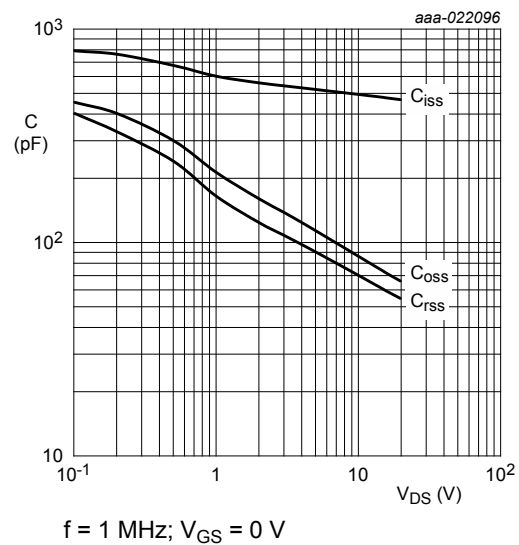


Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

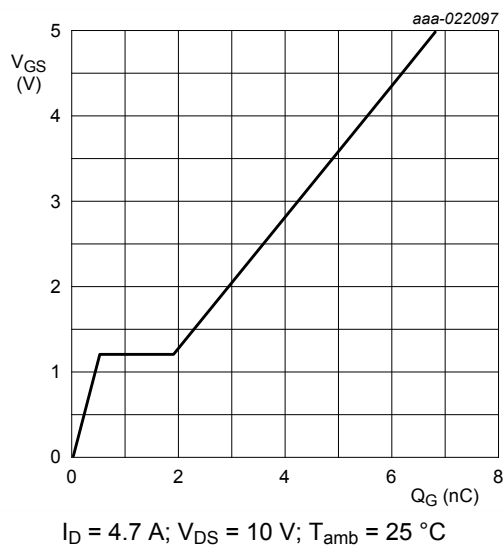


Fig. 14. Gate-source voltage as a function of gate charge; typical values

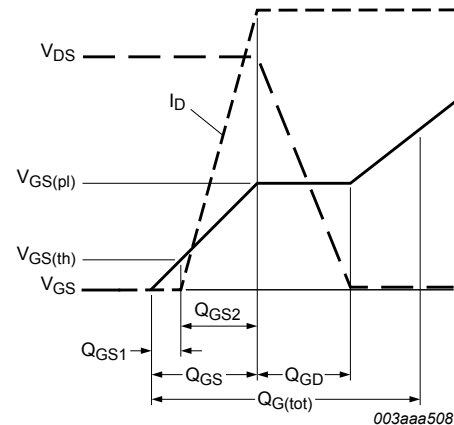


Fig. 15. Gate charge waveform definitions

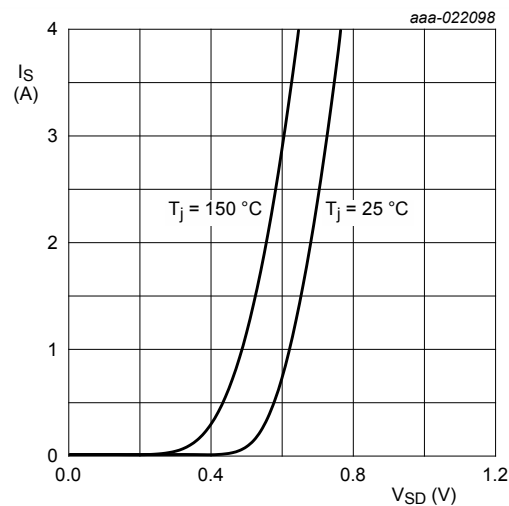
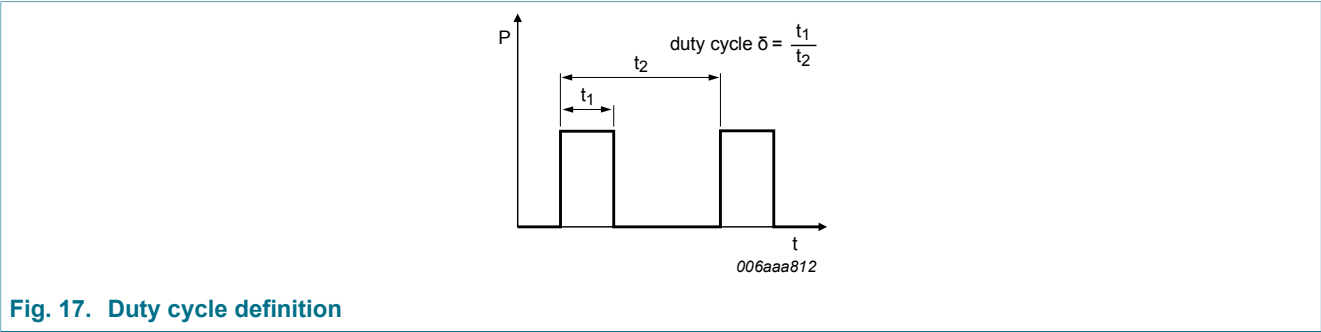
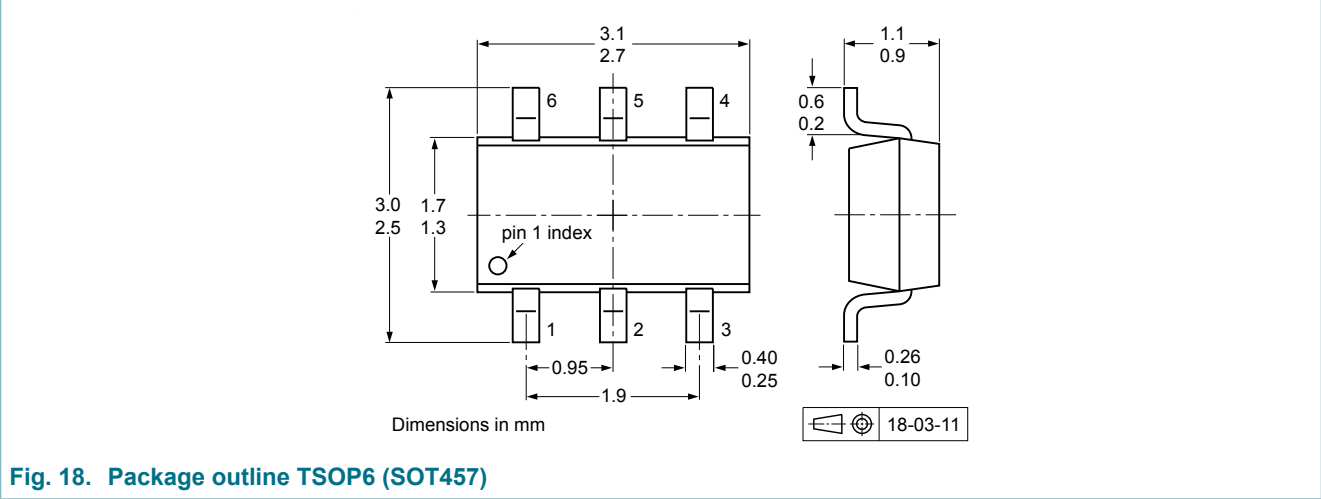


Fig. 16. Source current as a function of source-drain voltage; typical values

11. Test information



12. Package outline



13. Soldering

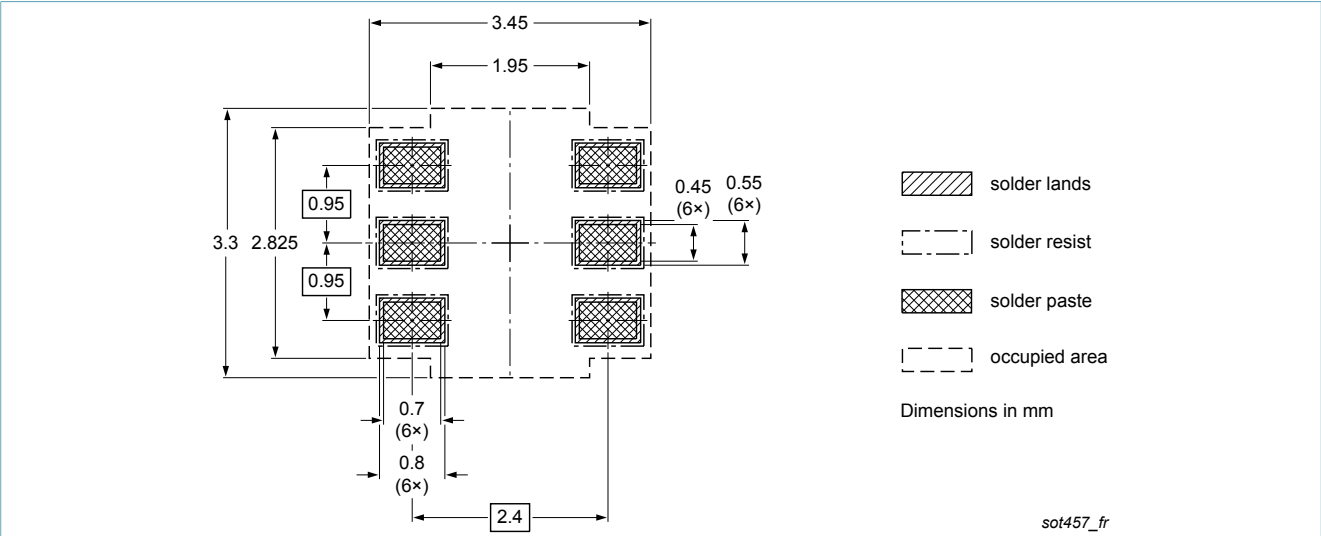


Fig. 19. Reflow soldering footprint for TSOP6 (SOT457)

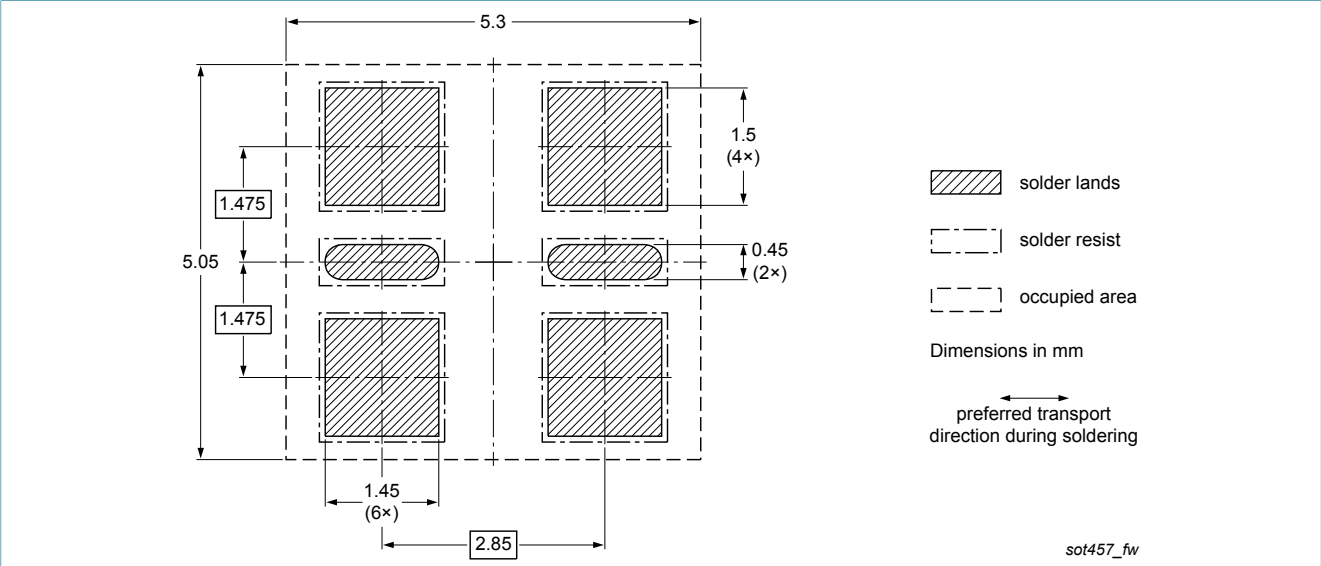


Fig. 20. Wave soldering footprint for TSOP6 (SOT457)

14. Revision history

Table 8. Revision history

| Data sheet ID | Release date | Data sheet status  | Change notice | Supersedes |
|---------------|--------------|--------------------|---------------|------------|
| PMN28UNE v.1  | 20180416     | Product data sheet | -             | -          |

## 15. Legal information

### Data sheet status

| Document status [1][2]         | Product status [3] | Definition                                                                            |
|--------------------------------|--------------------|---------------------------------------------------------------------------------------|
| Objective [short] data sheet   | Development        | This document contains data from the objective specification for product development. |
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Date of release: 16 April 2018